

MANUFACTURING APPARATUS OF SEMICONDUCTOR DEVICE AND SUBSTRATE CLEANING METHOD

ABSTRACT

5 A manufacturing apparatus (10) of a semiconductor device includes: a conveyance mechanism (16), conveying a substrate (100) in which a chip is mounted on a front surface to a downstream side of a predetermined conveyance direction in a posture in which a front surface of the substrate faces toward an upper side of a gravity direction; one or more roll brushes (30U, 30D), provided on a conveyance path of the substrate (100) and on a lower side with respect to a
10 conveyance height of the substrate (100), the one or more roll brushes cleaning a back surface (104) of the substrate (100) by rotating about an axis tilted with respect to the conveyance direction while contacting the back surface (104); and a suction mechanism (50), sucking a foreign matter scraped off by the one or more roll brushes (30U, 30D) via one or more suction holes (54).

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Figure 1